

# Technical Data Sheet

## ABLEBOND® 84-3

### One Component, Insulative Chip Adhesive

| TYPICAL PROPERTIES   | TEST METHOD | DESCRIPTION   |
|--|-------------|---|
| Viscosity @ 25°C: 50,000 cps   | PT-42       | <p>Ablebond® 84-3 one component, solvent-free epoxy chip adhesive is an electrically insulating version of Ablebond 84-1LMIT adhesive.</p> <p>This adhesive is designed to meet the requirements of Method 5011.</p> <p>Ablebond 84-3 adhesive is a soft, smooth paste, suitable for application by automatic dispensing, screen printing, or hand.</p> |
| Work Life @ 25°C: 2 weeks  | PT-54       |   |
| Cure Condition: 1 hour @ 150°C<br>Cure Option: 2 hours @ 125°C   |             |   |
| Die Shear Strength<br>(80 mil <sup>2</sup> IC)   | MT-4        |   |
| Au to Au @ 25°C: 6800 psi  |             |   |
| Volume Resistivity: 3.5 x 10 <sup>15</sup> ohm-cm  | PT-46       |   |
| Ionic Data   | CT-13       |   |
| Chloride: 130 ppm<br>Sodium: 10 ppm<br>Potassium: 30 ppm   |             |   |
| Water Extract  | CT-6        |   |
| Conductivity: 15 µmhos/cm<br>pH: 5.5   |             |   |
| Glass Transition Temperature (T <sub>g</sub> ): 85°C   | MT-9        |   |
| Coefficient of Thermal Expansion   | MT-9        |   |
| Below T <sub>g</sub> : 40 x 10 <sup>-6</sup> in/in/°C<br>Above T <sub>g</sub> : 10 x 10 <sup>-5</sup> in/in/°C |             |   |
| Weight Loss @ 300°C: 0.17%   | PT-20       |   |
| Thermal Conductivity @ 121°C: 0.48 BTU ft <sup>-1</sup> hr <sup>-1</sup> °F <sup>-1</sup>                      | PT-40       |   |
| Storage Life@ -40°C: 1 year  | PT-13       |   |

The figures shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.

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## INSTRUCTIONS

Apply adhesive as required. Assemble bonds. Cure at the recommended cure schedule(s).

## AVAILABILITY

Ablebond® 84-3 adhesive is available in a variety of package sizes, ranging from 1cc to 1 pound.

## STORAGE LIFE

This adhesive may be stored 1 year at -40°C.

## HEALTH AND SAFETY

**CAUTION** This product may cause skin irritation in sensitive persons. Avoid skin contact. If contact does occur, wash area immediately with soap and water. Please refer to Material Safety Data Sheet (OSHA) for more details.

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